



PATENT  
Attorney Docket No.: SSI-00501

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	)	Group Art Unit: 1763
Maximilian A. Biberger et al.	)	Examiner: Ram N. Kackar
Serial No.: 09/912,844	)	<b><u>TRANSMITTAL LETTER</u></b>
Filed: July 24, 2001	)	162 N. Wolfe Road
For: <b>HIGH PRESSURE PROCESSING</b>	)	Sunnyvale, CA 94086
<b>CHAMBER FOR</b>	)	(408) 530-9700
<b>SEMICONDUCTOR SUBSTRATE</b>	)	Customer No.: 28960

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313

Sir:

Enclosed please find a Supplemental Information Disclosure Statement and Form PTO-1449, including copies of the references contained thereon, for filing in the U.S. Patent and Trademark Office.

You will also find enclosed the associated Transmittals, Electronic Information Disclosure Statements, and United States Patent and Trademark Office Acknowledgment Receipts for the electronically filed Information Disclosure Statement (EFS ID #49914); (EFS ID #49915); (EFS ID#49916); and (EFS ID#49917) filed on October 29, 2003.

The Commissioner is hereby authorized to charge any additional fee or credit overpayment to our Deposit Account No. 08-1275. **An originally executed duplicate of this transmittal is enclosed for this purpose.**

Respectfully submitted,  
HAVERSTOCK & OWENS LLP

Dated: 10/29/03

By: Thomas B. Haverstock  
Thomas B. Haverstock  
Reg. No.: 32,571

Attorneys for Applicants

CERTIFICATE OF MAILING (37 CFR § 1.9(e))  
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HAVERSTOCK & OWENS LLP  
Date: 10-29-03 By: John D. Russell



Attorney Docket No.: PATENT  
SSI-00501

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:	)	Group Art Unit: 1763
Maximilian A. Biberger et al.	)	Examiner: Ram N. Kackar
Serial No.: 09/912,844	)	<b><u>SUPPLEMENTAL INFORMATION</u></b>
Filed: July 24, 2001	)	<b><u>DISCLOSURE STATEMENT</u></b>
For: <b>HIGH PRESSURE PROCESSING</b>	)	162 N. Wolfe Road
<b>CHAMBER FOR</b>	)	Sunnyvale, CA 94086
<b>SEMICONDUCTOR SUBSTRATE</b>	)	(408) 530-9700

\_\_\_\_\_  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313

Sir:

The citations listed below, copies attached, may be material to the examination of the above-identified application, and are therefore submitted in compliance with the duty of disclosure defined in 37 C.F.R. §§ 1.56 and 1.97. The Examiner is requested to make these citations of official record in this application.

United States Patents or Published Patent Applications have been filed electronically (EFS ID #49914); (EFS ID #49915); (EFS ID#49916); and (EFS ID#49917). Applicants have become aware of the following printed publication which may be material to the examination of this application:

- Chinese Publication No. CN 1399790 A;
- German Publication No. DE 36 08 783 A1;
- German Publication No. DE 198 60 084 A1;
- European Publication No. EP 0 244 951 A2;
- European Publication No. EP 0 272 141 A2;
- European Publication No. EP 0 453 867 A1;
- European Publication No. EP 0 572 913 A1;
- European Publication No. EP 0 587 168 A1;
- European Publication No. EP 0 679 753 B1;
- European Publication No. EP 0 903 775 A2;

- French Publication No. FR 1 499 491;
- Great Britain Publication No. GB 2 003 975;
  - Great Britain Publication No. GB 2 193 482;
  - Japanese Patent Abstract JP 2-148841;
  - Japanese Patent Abstract JP 2-209729;
  - Japanese Patent Abstract JP 11-200035;
  - Japanese Patent Abstract JP 56-142629;
  - Japanese Patent Abstract JP 60-238479;
  - Japanese Patent Abstract JP 60-246635;
  - Japanese Patent Abstract JP 61-231166;
  - Japanese Patent Abstract JP 62-125619;
  - Japanese Patent Abstract JP 63-303059;
  - Swiss Publication No. SE 251213;
  - PCT Publication No. WO 87/07309;
  - PCT Publication No. WO 00/36635;
  - PCT Publication No. WO 01/55628 A1;
  - PCT Publication No. WO 01/68279 A2;
  - PCT Publication No. WO 01/74538 A1;
  - PCT Publication No. WO 01/85391 A2;
  - PCT Publication No. WO 01/94782 A3;
  - PCT Publication No. WO 02/16051 A2;
  - PCT Publication No. WO 03/030219 A2;
  - Hideaki Itakura et al., "Multi-Chamber Dry Etching System", Solid State Technology, April 1982, pp. 209-214;
  - Sun, Y.P. et al., "Preparation of Polymer-Protected Semiconductor Nanoparticles Through the Rapid Expansion of Supercritical Fluid Solution," Chemical Physics Letters, pp. 585-588, May 22, 1998;
  - Dahmen, N. et al., "Supercritical Fluid Extraction of Grinding and Metal Cutting Waste Contaminated with Oils," Supercritical Fluids - Extraction and Pollution Prevention, ACS Symposium Series, Vol. 670, pp. 270-279, 21 Oct 1997;
  - Xu, C. et al., "Submicron-Sized Spherical Yttrium Oxide Based Phosphors Prepared by Supercritical CO<sub>2</sub>-Assisted aerosolization and pyrolysis," Appl. Phys. Lett., Vol. 71, No.12, September 22, 1997, pp. 1643-1645;

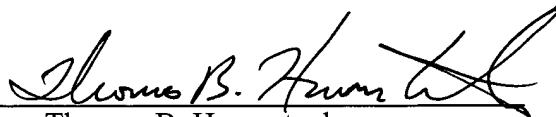
Courtecuisse, V.G. et al., "Kinetics of the Titanium Isopropoxide Decomposition in Supercritical Isopropyl Alcohol," Ind. Eng. Chem. Res., Vol. 35, No. 8, pp. 2539-2545, Aug 1996;

- Gallagher-Wetmore, P. et al., "Supercritical Fluid Processing: A New Dry Technique for Photoresist Developing," SPIE Vol. 2438, pp.694-708, Jun. 1995.
- Purtell, R, et al., "Precision Parts Cleaning using Supercritical Fluids," J. Vac, Sci, Technol. A. Vol. 11, No. 4, July 1993, pp. 1696-1701;
- Matson, D.W. et al., "Rapid Expansion of Supercritical Fluid Solutions: Solute Formation of Powders, Thin Films, and Fibers," Ind. Eng. Chem. Res., Vol. 26, No. 11, pp. 2298-2306, 1987;
- Tolley, W.K. et al., "Stripping Organics from Metal and Mineral Surfaces using Supercritical Fluids," Separation Science and Technology, Vol. 22, pp. 1087-1101, 1987;
- Joseph L. Foszcz, "Diaphragm Pumps Eliminate Seal Problems", Plant Engineering , pp. 1-5, February 1, 1996; and
- Bob Agnew, "WILDEN Air-Operated Diaphragm Pumps", Process & Industrial Training Technologies, Inc., 1996.

This Supplemental Information Disclosure Statement under 37 C.F.R. §§ 1.56 and 1.97 is not to be construed as a representation that a search has been made, that additional information material to the examination of this application does not exist, or that anyone or more of these citations constitutes prior art.

Respectfully submitted,  
HAVERSTOCK & OWENS LLP

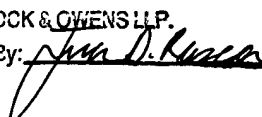
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By:   
Thomas B. Haverstock  
Reg. No.: 32,571

Attorneys for Applicants

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U.S. Department of Commerce  
Patent and Trademark Office

Attorney Docket No.: SSI-00501

Serial No.: 09/912,844

## INFORMATIONAL DISCLOSURE STATEMENT BY APPLICANT

(Use Several Sheets If Necessary)

Applicants: Maximilian A. Biberger et al.

(37 CFR § 1.98(b))

Filing Date: July 24, 2001

Group Art Unit: 1763

## FOREIGN PATENTS OR PUBLISHED FOREIGN PATENT APPLICATIONS

		Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation	
							Yes	No
	AA	CN 1399790 A	02/26/03	China	H01L	21/00		X
	AB	DE 36 08 783 A1	09/17/87	Germany	C30B	25/12		X
	AC	DE 198 60 084 A1	07/06/00	Germany	H01L	21/3213		X
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	AE	EP 0 272 141 A2	06/22/88	EPO	H01L	21/00		X
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	AH	EP 0 587 168 A1	03/16/94	EPO	B08B	7/00		X
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	AN	JP 2-148841	06/07/90	Japan	H01L	21/306		X
	AO	JP 2-209729	8/21/90	Japan	H01L	21/302		X
	AP	JP 11-200035	07/27/99	Japan	C23C	14/34		X
	AQ	JP 56-142629	11/07/81	Japan	H01L	21/205		X
	AR	JP 60-238479	11/27/85	Japan	C23C	14/56		X
	AS	JP 60-246635	12/06/85	Japan	H01L	21/302		X
	AT	JP 61-231166	10/15/86	Japan	C23C	14/24		X
	AU	JP 62-125619	06/06/87	Japan	H01L	21/30		X
	AV	JP 63-303059	12/09/88	Japan	C23C	14/22		X
	AW	SE 251213	08/16/48	Swiss	100a			X
	AX	WO 87/07309	12/03/87	PCT	C23C	16/00		X
	AY	WO 00/36635	06/22/00	PCT	H01L	21/00		X
	AZ	WO 01/55628 A1	08/02/01	PCT	F16K	51/02		X
	BA	WO 01/68279 A2	09/20/01	PCT	B08B	7/00		X
	BB	WO 01/74538 A1	10/11/01	PCT	B24C	1/00		X
	BC	WO 01/85391 A2	11/15/01	PCT	B24B			X
	BD	WO 01/94782 A3	12/13/01	PCT	F04B	43/02		X
	BE	WO 02/16051 A2	02/28/02	PCT	B05D			X
	BF	WO 03/030219 A2	10/04/03	PCT	H01L			X
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Patent and Trademark Office

Attorney Docket No.: SSI-00501

Serial No.: 09/912,844

## INFORMATION DISCLOSURE STATEMENT BY APPLICANT

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(37 CFR § 1.98(h))

Filing Date: July 24, 2001

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		Document Number	Publication Date	Country / Patent Office	Class	Subclass	Translation	
							Yes	No
	BJ							
	BK							
	BL							
	BM							
	BN							
	BO							

## OTHER DOCUMENTS (Including Author, Title, Date, Relevant Pages, Place of Publication)

	BP	Hideaki Itakura et al., "Multi-Chamber Dry Etching System", Solid State Technology, April 1982, pp. 209-214.
	BQ	Sun, Y.P. et al., "Preparation of Polymer-Protected Semiconductor Nanoparticles Through the Rapid Expansion of Supercritical Fluid Solution," Chemical Physics Letters, pp. 585-588, May 22, 1998.
	BR	Dahmen, N. et al., "Supercritical Fluid Extraction of Grinding and Metal Cutting Waste Contaminated with Oils," Supercritical Fluids - Extraction and Pollution Prevention, ACS Symposium Series, Vol. 670, pp. 270-279, 21 Oct 1997.
	BS	Xu, C. et al., "Submicron-Sized Spherical Yttrium Oxide Based Phosphors Prepared by Supercritical CO <sub>2</sub> -Assisted aerosolization and pyrolysis," Appl. Phys. Lett., Vol. 71, No.12, September 22, 1997, pp. 1643-1645.
	BT	Courtecuisse, V.G. et al., "Kinetics of the Titanium Isopropoxide Decomposition in Supercritical Isopropyl Alcohol," Ind. Eng. Chem. Res., Vol. 35, No. 8, pp. 2539-2545, Aug 1996.
	BU	Gallagher-Wetmore, P. et al., "Supercritical Fluid Processing: A New Dry Technique for Photoresist Developing," SPIE Vol. 2438, pp.694-708, Jun. 1995.
	BV	Purtell, R. et al., "Precision Parts Cleaning using Supercritical Fluids," J. Vac. Sci. Technol. A. Vol. 11, No. 4, July 1993, pp. 1696-1701.
	BW	Matson, D.W. et al., "Rapid Expansion of Supercritical Fluid Solutions: Solute Formation of Powders, Thin Films, and Fibers," Ind. Eng. Chem. Res., Vol. 26, No. 11, pp. 2298-2306, 1987.
	BX	Tolley, W.K. et al., "Stripping Organics from Metal and Mineral Surfaces using Supercritical Fluids," Separation Science and Technology, Vol. 22, pp. 1087-1101, 1987.
	BY	Joseph L. Foszcz, "Diaphragm Pumps Eliminate Seal Problems", Plant Engineering, pp. 1-5, February 1, 1996.
	BZ	Bob Agnew, "WILDEN Air-Operated Diaphragm Pumps", Process & Industrial Training Technologies, Inc., 1996.
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## FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

## Title of Invention

HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE

Application Number: 09/912844 \*09/912844\*

Date: 2001-07-24

First Named Applicant: Maximilian A. Biberger

Attorney Docket Number:

**TOTAL FEE AUTHORIZED \$180**

Patent fees are subject to annual revisions on or about October 1st of each year.

## BASIC FILING FEE

Fee Description	Fee Code	Amount \$	Fee Paid \$
Submission Of Information Disclosure Stmt Fee	1806	180	180

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Deposit authorized name: Thomas B. Haverstock

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Date (YYYYMMDD): 2003-10-29

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ACKNOWLEDGEMENT RECEIPT**

Electronic Version 1.1

Stylesheet Version v1.1.1

<b>Title of Invention</b>	<b>HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE</b>										
<b>Submission Type:</b>	Information Disclosure Statement										
<b>Application Number:</b>	09/912844	<b>*09/912844*</b>									
<b>EFS ID:</b>	49914										
<b>Server Response:</b>	<table border="1" style="width: 100%; border-collapse: collapse;"> <thead> <tr> <th style="width: 15%;">Confirmation Code</th> <th>Message</th> </tr> </thead> <tbody> <tr> <td>ISVR1</td> <td>Submission was successfully submitted - Even if Informational or Warning Messages appear below, please do not resubmit this application</td> </tr> <tr> <td>ICON1</td> <td>5915</td> </tr> <tr> <td>ISYS5</td> <td>Filename= N/A BusinessRule= Validation System/Function Call Information. #Supporting Msg:Server unable to validate the Confirmation/Application numbers at this time. They will be checked by PTO personnel later.</td> </tr> </tbody> </table>			Confirmation Code	Message	ISVR1	Submission was successfully submitted - Even if Informational or Warning Messages appear below, please do not resubmit this application	ICON1	5915	ISYS5	Filename= N/A BusinessRule= Validation System/Function Call Information. #Supporting Msg:Server unable to validate the Confirmation/Application numbers at this time. They will be checked by PTO personnel later.
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ICON1	5915										
ISYS5	Filename= N/A BusinessRule= Validation System/Function Call Information. #Supporting Msg:Server unable to validate the Confirmation/Application numbers at this time. They will be checked by PTO personnel later.										
<b>First Named Applicant:</b>	Maximilian Biberger										
<b>Attorney Docket Number:</b>											
<b>Timestamp:</b>	2003-10-29 12:27:57 EDT										
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## TRANSMITTAL

Electronic Version v1.1  
 Stylesheet Version v1.1.0

<b>Title of Invention</b>	<b>HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE</b>		
Application Number:	09/912844	*09/912844*	
Date:	2001-07-24		
First Named Applicant:	Maximilian A. Biberger		
Confirmation Number:	5915		
Attorney Docket Number:			
<p>I hereby certify that the use of this system is for OFFICIAL correspondence between patent applicants or their representatives and the USPTO. Fraudulent or other use besides the filing of official correspondence by authorized parties is strictly prohibited, and subject to a fine and/or imprisonment under applicable law.</p> <p>I, the undersigned, certify that I have viewed a display of document(s) being electronically submitted to the United States Patent and Trademark Office, using either the USPTO provided style sheet or software, and that this is the document(s) I intend for initiation or further prosecution of a patent application noted in the submission. This document(s) will become part of the official electronic record at the USPTO.</p>			
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Thomas B. Haverstock		/tbh/	Attorney
Registered Number: 32571			

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<b>Comments</b>	

## ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE						
Application Number:	09/912844 *09/912844*						
Confirmation Number:	5915						
First Named Applicant:	Maximilian Biberger						
Attorney Docket Number:							
Search string:	( 2617719 or 2625886 or 3744660 or 3968885 or 4029517 or 4091643 or 4245154 or 4341592 or 4355937 or 4367140 or 4406596 or 4422651 or 4474199 or 4522788 or 4549467 or 4592306 or 4601181 or 4626509 or 4670126 or 4682937 or 4693777 or 4749440 or 4778356 or 4789077 or 4823976 or 4825808 or 4827867 or 4838476 or 4865061 or 4879431 or 4917556 or 4924892 or 4951601 or 4960140 or 4983223 or 5011542 or 5044871 or 5062770 or 5071485 or 5105556 or 5167716 or 5169296 or 5169408 or 5186718 or 5188515 or 5190373 or 5191993 ).pn.						
<b>US Patent Documents</b>							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
Init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
	1	2617719	1952-11-11	C. R. Stewart			
	2	2625886	1953-01-20	Browne			
	3	3744660	1973-07-10	Gaines et al.			
	4	3968885	1976-07-13	Hassan et al.			
	5	4029517	1977-06-14	Rand			
	6	4091643	1978-05-30	Zucchini			
	7	4245154	1981-01-13	Uehara et al.			

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8	4341592	1982-07-27	Shortes et al.
9	4355937	1982-10-26	Mack et al.
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25	4823976	1989-04-25	White, III et al.
26	4825808	1989-05-02	Takahashi et al.
27	4827867	1989-05-09	Takel et al.
28	4838476	1989-06-13	Rahn
29	4865061	1989-09-12	Fowler et al.
30	4879431	1989-11-07	Bertoncini
31	4917556	1990-04-17	Stark et al.
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36	5011542	1991-04-30	Weil
37	5044871	1991-09-03	Davis et al.
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Init	Cite.No.	Patent No.	Date	Patentee
	40	5105556	1992-04-21	Kurokawa et al.
	41	5167716	1992-12-01	Boltnott et al.
	42	5169296	1992-12-08	Wilden
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	46	5190373	1993-03-02	Dickson et al.
	47	5191993	1993-03-09	Wanger et al.

**Remarks**

Note: Remarks are not for responding to an office action.

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<b>Application Number:</b>	09/912844	<b>*09/912844*</b>									
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10/29/2003

TRANSMITTAL		
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<b>Title of Invention</b>	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE	
Application Number:	09/912844 *09/912844*	
Date:	2001-07-24	
First Named Applicant:	Maximilian A. Biberger	
Confirmation Number:	5915	
Attorney Docket Number:		
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Submitted by:	Elec. Sign.	Sign. Capacity
Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney

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Stylesheet Version v18.0

Title of Invention	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE						
Application Number:	09/912844						
Confirmation Number:	5915						
First Named Applicant:	Maximilian Biberger						
Attorney Docket Number:							
Search string:	( 5193560 or 5195878 or 5213485 or 5221019 or 5222876 or 5224504 or 5236669 or 5240390 or 5243821 or 5246500 or 5251776 or 5280693 or 5285352 or 5288333 or 5339844 or 5370741 or 5412958 or 5433334 or 5447294 or 5503176 or 5505219 or 5509431 or 5571330 or 5589224 or 5621982 or 5629918 or 5644855 or 5649809 or 5656097 or 5669251 or 5702228 or 5706319 or 5746008 ).pn.						
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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1	1	5193560	1993-03-16	Tanaka et al.			
2	2	5195878	1993-03-23	Sahliavo et al.			
3	3	5213485	1993-05-25	Wilden			
4	4	5221019	1993-06-22	Pechacek			
5	5	5222876	1993-06-29	Budde			
6	6	5224504	1993-07-06	Thompson et al.			
7	7	5236669	1993-08-17	Simmons et al.			
8	8	5240390	1993-08-31	Kvinge et al.			
9	9	5243821	1993-09-14	Schuck et al.			
10	10	5246500	1993-09-21	Samata et al.			

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Information Disclosure Statement

Page 3 of 3

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12	5280693	1994-01-25	Heudecker
13	5285352	1994-02-08	Pastore et al.
14	5288333	1994-02-22	Tanaka et al.
15	5339844	1994-08-23	Stanford Jr. et al.
16	5370741	1994-12-06	Bergman
17	5412958	1995-05-09	Iliff et al.
18	5433334	1995-07-18	Reneau
19	5447294	1995-09-05	Sakata et al.
20	5503176	1996-04-02	Dunmire et al.
21	5505219	1996-04-09	Lansberry et al.
22	5509431	1996-04-23	Smith, Jr. et al.
23	5571330	1996-11-05	Kyogoku
24	5589224	1996-12-31	Tepman et al.
25	5621982	1997-04-22	Yamashita et al.
26	5629918	1997-05-13	Ho et al.
27	5644855	1997-07-08	McDermott et al.
28	5649809	1997-07-22	Stapelfeldt
29	5656097	1997-08-12	Olesen et al.
30	5669251	1997-09-23	Townsend et al.
31	5702228	1997-12-30	Tamai et al.
32	5706319	1998-01-06	Holtz
33	5746008	1998-05-05	Yamashita et al.

## Remarks

Note: Remarks are not for responding to an office action.

Non US Patent and Publication references shall be filed under a separate paper transmittal.  
The current electronic filing contains part 2 out of a total of 4 electronic filings. Fee has been paid in previous electronic filing.

## Signature

UNITED STATES PATENT AND TRADEMARK OFFICE  
ACKNOWLEDGEMENT RECEIPT

Electronic Version 1.1

Stylesheet Version v1.1.1

Title of Invention	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE										
Submission Type:	Information Disclosure Statement										
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<b>Title of Invention</b>	<b>HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE</b>						
Application Number:	09/912844 *09/912844*						
Date:	2001-07-24						
First Named Applicant:	Maximilian A. Biberger						
Confirmation Number:	5915						
Attorney Docket Number:							
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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Thomas B. Haverstock Registered Number: 32571</td><td>/tbh/</td><td>Attorney</td></tr></tbody></table>		Submitted by:	Elec. Sign.	Sign. Capacity	Thomas B. Haverstock Registered Number: 32571	/tbh/	Attorney
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Title of Invention	HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR SUBSTRATE						
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Confirmation Number:	5915						
First Named Applicant:	Maximilian Biberger						
Attorney Docket Number:							
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Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
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*	1	5900107	1999-05-04	Murphy et al.			
	2	5904737	1999-05-18	Preston et al.			
	3	5932100	1999-08-03	Yager et al.			
	4	5934991	1999-08-10	Rush			
	5	5981399	1999-11-09	Kawamura et al.			
	6	5989342	1999-11-23	Ikeda et al.			
	7	6005226	1999-12-21	Aschner et al.			
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14	6082150	2000-07-04	Stucker	
15	6085935	2000-07-11	Malchow et al.	
16	6097015	2000-08-01	McCullough et al.	
17	6128830	2000-10-10	Bettcher et al.	
18	6145519	2000-11-14	Konishi et al.	
19	6159295	2000-12-12	Maskara et al.	
20	6164297	2000-12-26	Kamikawa	
21	6203582	2001-03-20	Berner et al.	B1
22	6216364	2001-04-17	Tanaka et al.	B1
23	6239038	2001-05-29	Wen	B1
24	6241825	2001-06-05	Wytman	B1
25	6251250	2001-06-26	Keigler	B1
26	6277753	2001-08-21	Mullee et al.	B1
27	6286231	2001-09-11	Bergman et al.	B1
28	6305677	2001-10-23	Lenz	B1
29	6334266	2002-01-01	Moritz et al.	B1
30	6344174	2002-02-05	Miller et al.	B1
31	6388317	2002-05-14	Reese	B1
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33	6418956	2002-07-16	Bloom	B1
34	6436824	2002-08-20	Chooi et al.	B1
35	6454945	2002-09-24	Weigl et al.	B1
36	6464790	2002-10-15	Shertinsky et al.	B1

## Remarks

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Non US Patent and Publication references shall be filed under a separate paper transmittal.



**UNITED STATES PATENT AND TRADEMARK OFFICE  
ACKNOWLEDGEMENT RECEIPT**

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Stylesheet Version v1.1.1

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Application Number:	09/912844      *09/912844*						
Date:	2001-07-24						
First Named Applicant:	Thomas B. Haverstock						
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Attorney Docket Number:							
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<b>Submitted by:</b>	<b>Elec. Sign.</b>	<b>Sign. Capacity</b>					
Maximilian A. Biberger Registered Number: 32571	/tbh/	Attorney					

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**ELECTRONIC INFORMATION DISCLOSURE STATEMENT**

Electronic Version v1.8

Stylesheet Version v1.8.0

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Invention**HIGH PRESSURE PROCESSING CHAMBER FOR SEMICONDUCTOR  
SUBSTRATE**

Application Number: 09/912844 \*09/912844\*  
Confirmation Number: 5915  
First Named Applicant: Thomas Haverstock  
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**US Patent Documents**

Note: Applicant is not required to submit a paper copy of cited US Patent Documents

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	1	6521466	2002-02-18	Castrucci	BI		
	2	6541278	2003-04-01	Morita et al.	BI		
	3	6546946	2003-04-15	Dunmire	BI		
	4	6550484	2003-04-22	Gopinath et al.	BI		
	5	6558475	2003-05-06	Jur et al.	BI		
	6	6561213	2003-05-13	Wang et al.	BI		
	7	6561220	2003-05-13	McCullough et al.	BI		
	8	6561481	2003-05-13	Filonczuk	BI		
	9	6561767	2003-05-13	Biberger et al.	BI		
	10	6564826	2003-05-20	Shen	BI		
	11	5217043	1993-06-08	Novakovi			

**US Published Applications**

Note: Applicant is not required to submit a paper copy of cited US Published Applications

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**Remarks**

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The current electronic filing contains part 4 out of a total of 4 electronic filings. Fee has been  
paid in previous electronic filing.

**Signature**

Examiner Name	Date